EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1341	15/77.ccls.	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/13 15:25
L2	84	15/77.ccls. and wafer and conve$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/13 15:26

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L9: Entry 8 of 8   File: DWPI   May 9, 2000

DERWENT-ACC-NO: 2000-399041
DERWENT-WEEK: 200034
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TITLE: Double sided scrubber system used for cleaning a wafer

INVENTOR: HILLMAN, G

PATENT-ASSIGNEE:
ASSIGNEE   CODE
CREATIVE DESIGN CORP   CREAN

PRIORITY-DATA: 1997US-065714P (November 14, 1997), 1998US-0191691 (November 13, 1998)

Search Selected   Search ALL   Clear

PATENT-FAMILY:

	PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
☐	US 6059888 A	May 9, 2000		013	B08B007/00

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
US 6059888A	November 14, 1997	1997US-065714P	Provisional
US 6059888A	November 13, 1998	1998US-0191691	

INT-CL (IPC): A47 L 1/02; B08 B 7/00

ABSTRACTED-PUB-NO: US 6059888A
BASIC-ABSTRACT:

NOVELTY - The differential frictional forces on the opposite sides of the center of a wafer (202) produces a torque on the wafer about a center causing the wafer to rotate about a central axis (201) transverse to the scrubber axes and the top and bottom surfaces of the wafer. The wafer is kept in position by the constraints (264) as the wafer rotates. The constraints prohibit the translation of the wafer.

DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for a wafer cleaning method.

USE - Used for cleaning a wafer.

ADVANTAGE - Provides a simple and reliable system for subjecting all surfaces of a wafer to scrubbing.

DESCRIPTION OF DRAWING(S) - The figure shows the perspective view of the scrubber system.

Central axis 201

Wafer 202

Constraints 264

CHOSEN-DRAWING: Dwg.1/11

TITLE-TERMS: DOUBLE SIDE SCRUB SYSTEM CLEAN WAFER

DERWENT-CLASS: P28 P43 U11 X25

EPI-CODES: U11-C06A1B; X25-H09;

SECONDARY-ACC-NO:
Non-CPI Secondary Accession Numbers: N2000-298917